

Appl. No. 10/043,400
Amdt. Dated July 7, 2003
Reply to Office Action of April 7, 2003

REMARKS

This communication is in response to the Examiner's Office Action dated 04/07/2003.

Reconsideration of the above-mentioned application is hereby requested in view of the above amendments and remarks which follows.

Applicants appreciate the Examiner's thoughtful consideration of Applicants' application, and in the indication of allowable subject matter in claims 2-8 and 11-18. Claims 1, 9, 10, 19, and 20 are rejected herein.

The Examiner rejected claims 9-20 under 35 U.S.C. §112, second paragraph, as failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. More particularly, the Examiner was unclear as to the limitation, "a resilient spacer positioned between said substrate and said housing." Applicants respectfully disagree with the Examiner, that the language is unclear and that it is contradictory to the specification. Rather, the resilient spacer, and in particular the resilient arms 72 space the substrate 6 in a resilient manner away from the substrate receiving face of the housing as shown, for example, in Figures 7, 8 and 12. However, when a chip is received in the housing and the assembly is situated on a board 160, the resilient arms of the housing allow the substrate to move upwardly towards the substrate receiving face 54, whereby the contacts 102 extend through their openings to contact pads 152 on chip 150.

The Examiner rejected claim 1 under 35 U.S.C. §103(a) as being unpatentable over McHugh, et al. (U.S. Patent 6,179,624) in view of McHugh, et al. (U.S. Patent 6,244,875). The '624 patent shows a housing 6 having a contact 5 to receive an IC package. The Examiner combined McHugh, et al.'s '875 patent, as the Examiner indicated that the '875 patent showed resilient arms at

27. The arms 27, however, are board-lock members which are configured to be received in a throughhole of a board to which it is connected, and the resiliency is in a direction generally in the plane of the board to which it is connected.

Applicants have amended claim 1 to more particularly point out that the resilient arm is resilient in a direction perpendicular to the lower substrate receiving face, which thereby allows the substrate to move towards and away from the substrate receiving face. This is neither shown by McHugh, et al.'s '624 nor '875.

The Examiner also rejected claim 9 under 35 U.S.C. §103(a) as being unpatentable over McHugh, et al.'s '624 in view of Newell (U.S. Patent 4,831,359). The Examiner indicated that McHugh, et al. disclose all of the invention as claimed with the exception of the resilient spacer, and that Newell teaches a resilient spacer 42.

Firstly, Newell has absolutely nothing to do with a chip carrier socket or the interconnection of an IC chip, but rather, is a touch pad including sensors, such as optoelectric switches 32-38. The sensor 10 includes a box-like base 12, which holds a printed circuit board 28 in a fixed position relative to posts 26. (See column 3, lines 13-17.) A fastener such as 52 passes through the bottom of the base 12 and is received in a center post 48 of a touch panel member 44. Resilient spacers such as 42 are positioned between the circuit board 28 and touch panel member 44. The touch panel member 44 can be contacted so as to be rocked relative to the printed circuit board, whereby the optoelectric switches are effected (see column 3, lines 50-53, and column 3, lines 60-66).

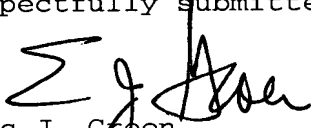
Thus, while Applicants believe that McHugh, et al., '624 and Newell is not a proper combination, even if the combination is proper, it does not teach the invention as claimed by Applicants in claim 9.

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Applicants' claim 9 includes a resilient spacer positioned between the substrate of the housing, where the substrate is deformable to a position where the leads extend through the chip receiving face. Since the leads are part of the substrate, it is clear that the substrate moves relative to the housing, such that the substrate leads move from a position where their contact ends are positioned below the chip receiving face to a position where the leads extend through the chip receiving face. Newell has no such teaching and therefore the combination of McHugh and Newell cannot teach the subject matter of claim 9.

For all the foregoing amendments and comments, Applicants believe that all of the claims 1-20 are now in condition for allowance, and respectfully request early passage thereof.

Respectfully submitted,


Eric J. Groen
Registration No. 32,230
Attorney for Applicant
BAKER & DANIELS
205 West Jefferson Blvd., Suite 250
South Bend, IN 46601
Tel: (574)234-4149
Fax: (574)239-1900

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Eric J. Groen, Reg. No. 32,230